

C1825X332MFGACTU

Aliases (C1825X332MFGAC7800) SMD Comm COG HV Flex, Ceramic, 3,300 pF, 20%, 1,500 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1825, 2.3 mm



General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra- Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	230 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1825
L	4.6mm +/-0.4mm
W	6.4mm +/-0.4mm
т	1.6mm +/-0.20mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Click here for the 3D model.

Packaging Specifications Packaging T

PackagingT&R, 180mm, Plastic TapePackaging Quantity1000

Specifications	
Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	1500 VDC
Dielectric Withstanding Voltage	1,800 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.